

Pressrelease

30/09/2010

AT&S at electronica 2010 international trade fair in Munich

Innovative embedded components packaging technology is one of the highlights of AT&S's newly designed stand at electronica 2010.

Innovative, youthful and dynamic – this is how AT&S is presenting its extensive product portfolio and technical innovations at its new stand at the industry's international trade fair in Munich. Each of the three competence clusters is dedicated to one of the Group's core businesses – Mobile Devices, Automotive and Industrial. electronica is the world's leading exhibition for components, systems and applications, and takes place this year from 9-12 November in Munich. The AT&S stand is Stand 125 in Hall B1.

Ever smaller devices with increasingly complex specifications are the challenge of the future. "Innovative ability and continuing technological development are the core drivers of our corporate strategy," explains AT&S CEO Andreas Gerstenmayer. "AT&S's embedded component packaging technology is its investment in the future of the printed circuit board – ECP® is a highly efficient technology for the integration of active and passive electronic components inside printed circuit boards." ECP® makes a wide range of applications possible, from single chip modules and printed circuit boards to complex system-in-package modules and system-in-board applications.

With printed circuit board factories in Austria – including Europe's biggest HDI printed circuit board facility in Leoben-Hinterberg – in India, in China and in Korea, AT&S is a global partner with the ability to react quickly and flexibly to customers' requirements and to provide active support to customers in the further development of their products. As by far the largest producer of printed circuit boards in Europe, AT&S has set itself the goal of making end products of the highest possible quality at the lowest possible cost.

Additional services such as design solutions, extensive supply chain expertise, and the advantages of one-stop shopping complete the offering, making AT&S a long-term, financially reliable business partner in the automotive, industrial and mobile devices sectors.

AT&S's key technologies at electronica 2010

- ECP® – embedded component packaging technology
- 2.5D™ technology
- Rigid-flex printed circuit boards
- HDI microvia printed circuit boards
- Micro-conductor technology
- HSMtec technology

AT&S product portfolio

- Single-sided printed circuit boards
- Insulated metallic substrate (IMS)
- Double-sided through-hole plated printed circuit boards
- Multilayer printed circuit boards (up to 22 layers)
- HDI microvia printed circuit boards
- Semi-flexible printed circuit boards
- Flexible printed circuit boards
- Rigid-flex printed circuit boards

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About AT&S

AT&S Austria Technologie & Systemtechnik Aktiengesellschaft (AT&S) is European market leader and one of the world's strongest-performing printed circuit board manufacturers. AT&S is especially well positioned worldwide in the high-tech market segment for HDI microvia printed circuit boards, which are chiefly used in mobile devices. The Group is also highly successful in the automotive printed circuit board market, and in the industrial and medical technology sectors. As a vigorous and growing international enterprise, AT&S has a global presence, with three production facilities in Austria (Leoben, Fehring, Klagenfurt) and one each in India (Nanjangud), China (Shanghai) and Korea (Ansan, near Seoul).

For more information visit www.ats.net.

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